



Material Content Data Sheet



Sales Product Name		IDH05S120		Issued		20. July 2018		
MA#		MA000622908						
Package		PG-TO220-2-1		Weight*		1969.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.515	0.13	0.13	1277	1277
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		382	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.18	38.23	381638	382136
wire	non noble metal	aluminium	7429-90-5	0.683	0.03	0.03	347	347
encapsulation	organic material	carbon black	1333-86-4	9.070	0.46		4604	
	plastics	epoxy resin	-	99.768	5.06		50646	
	inorganic material	silicondioxide	60676-86-0	495.819	25.17	30.69	251696	306946
leadfinish	non noble metal	tin	7440-31-5	14.668	0.74	0.74	7446	7446
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	101
solder	noble metal	silver	7440-22-4	0.105	0.01		53	
	non noble metal	tin	7440-31-5	0.084	0.00		42	
	non noble metal	lead	7439-92-1	3.994	0.20	0.21	2028	2123
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		300	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	copper	7440-50-8	589.466	29.92	29.96	299234	299624
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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